

segments, whereby the adhesion between said encapsulation material and said surrounded parts is maximized; and
said encapsulation material leaving said second ends of said lead segments exposed, whereby the solder attachment to said gold layer is maximized.]

Cancel claim 14.

Remarks

Favorable reconsideration and allowance of the application are respectfully requested in view of the above amendments and the following comments.

The rejection of claim 1 as unpatentable over Okinaga, et al. is respectfully traversed, since the reference fails to disclose or suggest the invention as defined by the claims, particularly as now amended. Note specifically that gold-plated areas 2b of the reference are not external to the device package, and are intended for wire bonding, not solder attachment. Moreover, part 12 in Fig. 5 of the reference is not gold-plated, is not external to the package, and is not for solder attachment. The rejection is therefore improper and should be withdrawn.

The rejection of claim 1 as unpatentable over Akino, et al. is respectfully traversed, since the reference fails to disclose or suggest the invention as defined by the claim. Note specifically that Akino, et al. plates the entire leadframe, equally, without selectivity. Such prior art is expressly acknowledged in applicants' specification at page 3, lines 18-28. The disadvantages of total-area gold plating are quite severe, as explained in this portion of applicants' specification. The rejection is therefore improper and should be withdrawn.

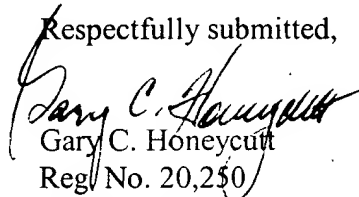
The rejection of claims 2-9, 11-13 and 15 as unpatentable over Abbott in view of Akino, et al. is respectfully traversed, since the references fail to disclose or suggest the invention as defined by applicants' claims. Neither reference provides any selective

plating of any leadframe segment, and therefore the combination of references is irrelevant. The rejection is improper and should be withdrawn.

Since Tsuji, et al. and Kom, et al. were fully discussed in a previous Amendment, applicants believe it was not intended by the Examiner to again comment on them. (See page 5, second full paragraph of the Office Action.) Since the Office Action clearly states that only "new grounds" of rejection are asserted, the reference to Tsuji and Kom appears to have been inadvertent.

The application is now believed to be in condition for allowance.

Respectfully submitted,



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